



- Used in SMPS Flyback Topology
- Designed for use with Power Integration Chip
- Reinforced Insulation (Triple Insulated Wire)
- UL 94V-0 Recognized Components
- UL 1446 Class F Insulation System
- Very Low Core Loss
- Add “-LF” after part number for Lead Free

### Electrical Parameters @ 25°C

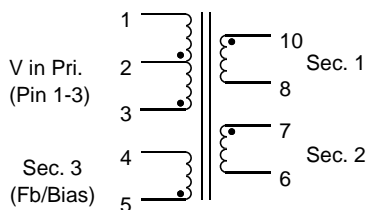
PCA Part Number	Chipset	Voltage (Vdc)				Primary OCL (µH ± 10%) @ 10 KHz, 0.1 Vrms	Current (Amp.)			Package
		V in Pin 1-3	V out 1	V out 2	V out 3		Sec. 1	Sec. 2	Sec. 3	
EPC3132-1A(-LF)	TNY264P (132 KHz)	120-375	9	N	N	2000	0.330	N	N	A
EPC3132-2A(-LF)	TNY264P(132 KHz)	120-375	5	N	12	1900	0.600	N	0.05	A
EPC3132-3A(-LF)	TOP221P (100 KHz)	120-375	5.1	N	N	1400	0.100	N	N	A
*EPC3132-4A(-LF)	LNK501 (42 KHz)	120-375	5.5	N	N	2550	0.500	N	N	B
*EPC3132-5A(-LF)	LNK501 (42 KHz)	120-375	5.5	N	N	1360	0.273	N	N	B
*EPC3132-6A(-LF)	TNY264P (132 KHz)	120-375	5.2	10.5	N	2400	0.600	0.015	N	B
EPC3132-7A(-LF)	TNY264P (132 KHz)	120-375	5.2	12.0	N	2400	0.600	0.015	N	A
EPC3132-8A(-LF)	TNY264P (132 KHz)	120-375	3.3	N	12	1900	0.600	N	0.05	A

- **Switching Frequency** : 132 KHz/100 KHz/42 KHz
- **Isolation** : 3750 Vdc
- **\*Copper Flux Band** : is connected to Pin #3

Dielectric Rating (Vdc)		
1 sec. 4500 or 60 sec. 3750	1 sec. 4500 or 60 sec. 3750	1 sec. 1500 or 60 sec. 1000
Pri. to all Sec. Wdg's	Between Sec. Wdg's to Core	Between Pri. Wdg & Bias

- **Note** : “N” means Not Required/No Connections
- **Marking** : Mark on top or side

### Schematic

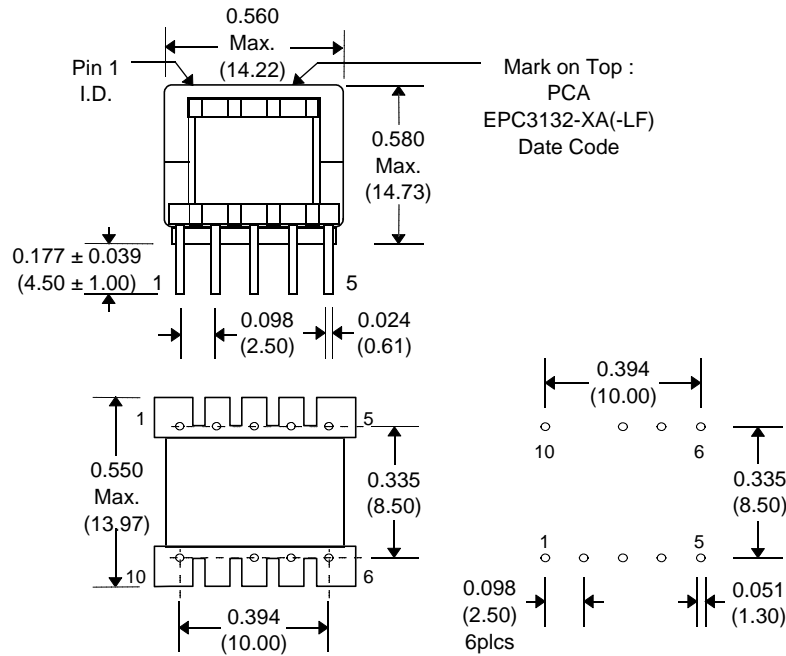


Pin #2 is not connected in circuit  
Pin #9 is omitted

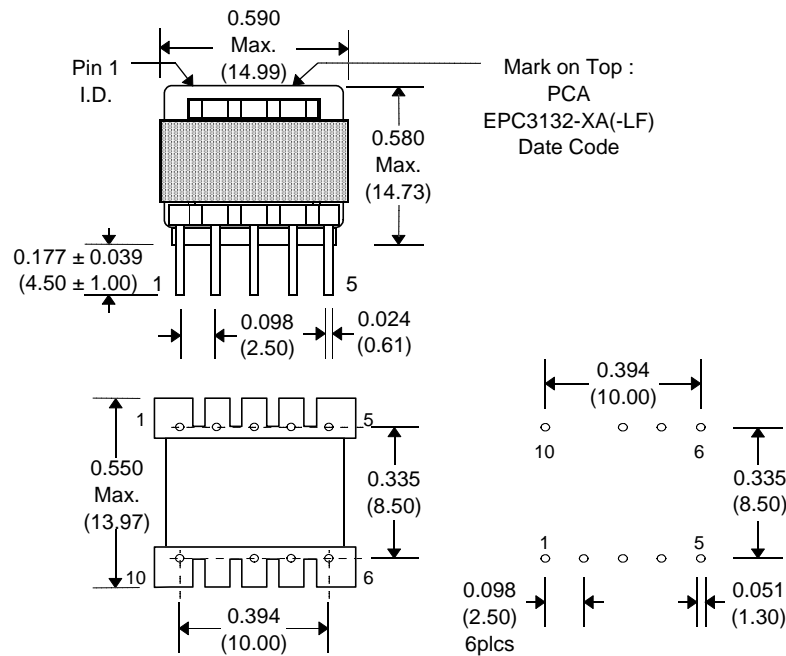
Notes :	EPC3132-XA	EPC3132-XA-LF
1. Lead Finish	Hot Dip SnPb	Hot Dip Sn or SnCu
2. Peak Solder Rating	260°C	260°C
3. Moisture Sensitive Levels (MSL)	1	1
4. Weight	4.21 gms	4.21 gms
5. Packaging Information (Tray)	80 pcs / tray	80 pcs / tray

Unless Otherwise Specified Dimensions are in Inches /mm ± .010 /.25

### Package A



### Package B



Unless Otherwise Specified Dimensions are in Inches /mm ± .010 / .25